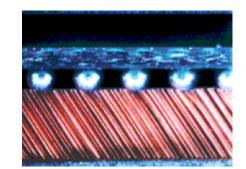
GHz BGA Socket - Direct mount, solderless **Features**

□ 12.225

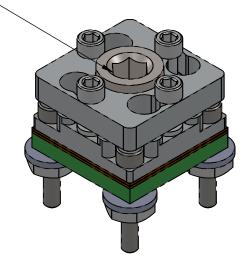
- Directly mounts to target PCB (needs tooling holes) with hardware
 High speed, reliable Elastomer connection
 Minimum real estate required

- Compression plate distributes forces evenly
 Ball guide prevents over compression of elastomer
 Easily removable swivel socket lid



Cross-section of BGA compressed on elastomer

-RECOMMENDED TORQUE:8.5 N-cm[0.75 lbf-in]



7.88		
_1		1.9050 6.13

Description: SG25-BGA 2.76x2.76mm 13x8 array 0.35

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG25-BGA-2016 Drawing

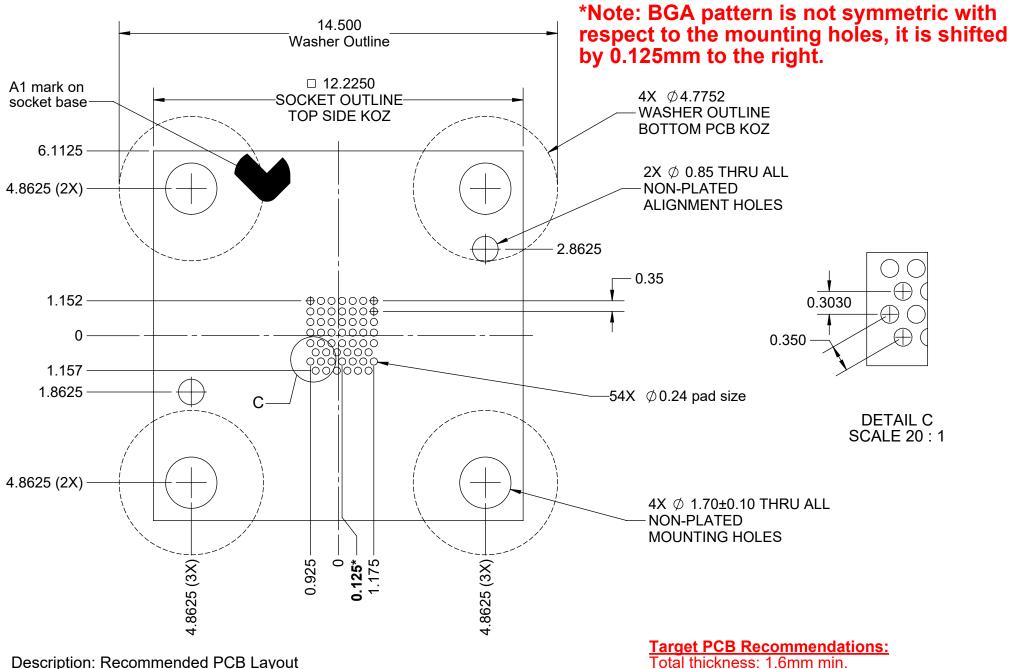


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Tele: (800) 404-0204
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□14.50

Material: N/A Finish: N/A ronics, Inc. Weight: 4.31

STA	TUS: Released	SHEET: 1 OF 4	REV. A
ENG	: J. Vavra	DRAWN BY: M. Raske	SCALE: 4:1
FILE	: SG25-BGA-2016 Dwg	DATE: 11/11/2015	



Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.025mm [±0.001"], Hole and pad positions ±0.025mm [±0.001"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

Plating: Gold or Solder finish PCB Pad height: Same or higher than solder mask

SG25-BGA-2016 Drawing			STATUS: Released SHEET: 2 OF 4 F	REV. A	
	©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Weight: 4.31	ENG: J. Vavra	DRAWN BY: M. Raske	SCALE: 8:1
			FILE: SG25-BGA-2016 Dwg	DATE: 11/11/2015	

IRONWOOD PACKAGE CODE: BGA54E

DIM

А

A1

b

D

Е

е

MIN

0.41

0.15

0.20

2.72

2.72

MAX

0.53

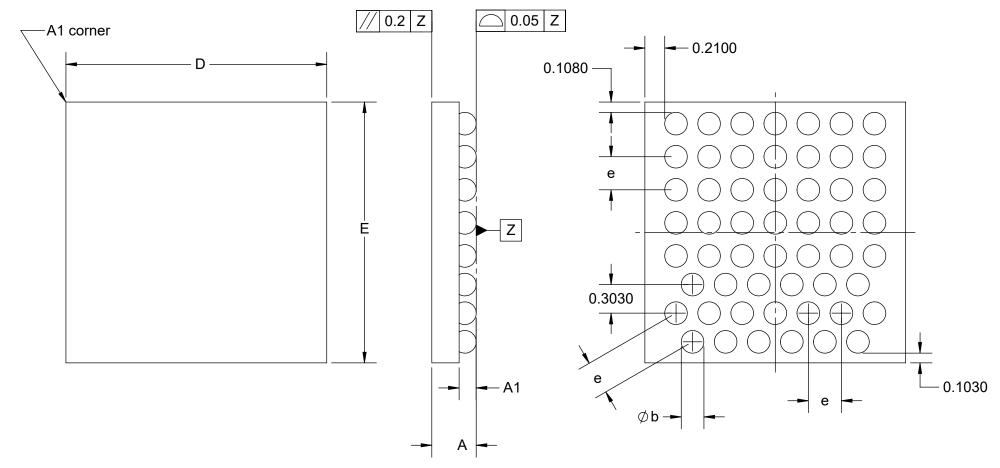
0.21

0.28

2.8

2.8

0.35



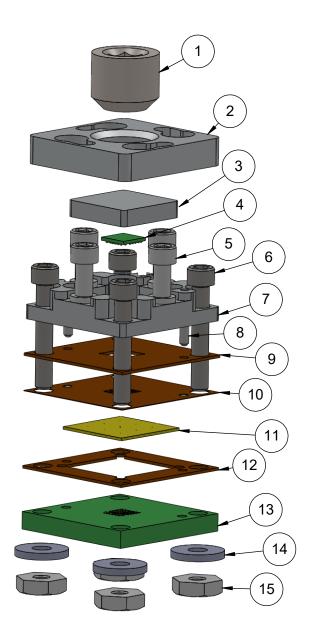
Dimensions are in millimeters.

- 1.
- Interpret dimensions and tolerances per ASME Y14.5M-1994. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z. 2.
- 3.
- Datum Z (seating plane) is defined by the spherical crowns of the solder balls. Parallelism measurement shall exclude any effect of mark on top surface of package. 4.

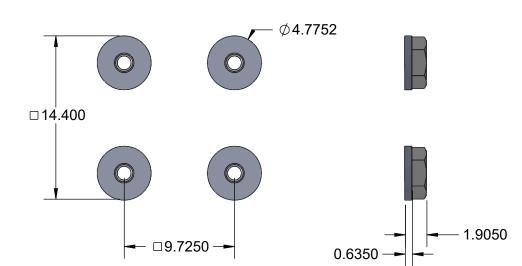
Description: Compatible Device

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG25-BGA-2016 Drawing Material: N/A		STATUS: Released	SHEET: 3 OF 4	REV. A
©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204	Finish: N/A Weight: 4.31	ENG: J. Vavra	DRAWN BY: M. Raske	SCALE: 25:1
www.ironwoodelectronics.com	5	FILE: SG25-BGA-2016 Dwg	DATE: 11/11/2015	



ITEM NO.	DESCRIPTION	Material
1	Compression Screw	Steel
2	Socket Lid	Aluminum
3	Compression Plate	Aluminum
4	Compatible BGA	N/A
5	Shoulder Screw	Steel
6	Mounting Screw	Steel
7	Socket Base	Aluminum
8	Alignment Pin	Steel
9	IC guide	Kapton Polyimide
10	Ball guide	Kapton Polyimide
11	Elastomer	Gold plated brass filaments in silicon rubber
12	Elastomer guide	Kapton Polyimide
13	Target PCB	N/A
14	Washer	Nylon
15	Nut	Steel
		-



Description: Socket, Backing Plate Detail

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances</u>: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG25-BGA-2016 Drawing

8

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Material: N/A Finish: N/A Weight: 4.31

WASHERS/NUTS MOUNTING POSITION DETAIL

STATUS: Released	SHEET: 4 OF 4	REV. A
ENG: J. Vavra	DRAWN BY: M. Raske	SCALE: 3:1
FILE: SG25-BGA-2016 Dwg	DATE: 11/11/2015	